Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		228/4.5.ccls..ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:30
		L1 or L2 or L3 or L5 or L6 or L7 or L8 or L9 or L10 or L11 or L12 or L13 or L14 or L15 or s`5 or L16 or L17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
		ceramic.clm. and capillary.clm. and bonding.clm. and (binder same thermoplastic)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:25
		ceramic.clm. and capillary.clm. and bonding.clm. and (binder same thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:23
		ceramic.clm. and capillary.clm. and (binder same thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:17
		ceramic.clm. and capillary.clm. and bonding.clm. and (binder same thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:25
L1	898	capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:28
L2	431	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:28

L3	212	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:28
L4	898	L1 or L2 or L3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:28
L5	73	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L6	0	ceramic.clm. and capillary.in. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L7	0	ceramic.clm. and capillary.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L8	572	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L9	181	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L10	57	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29

L11	572	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L12	34	ceramic.clm. and capillary.clm. and "264"/$8.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L13	181	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L14	57	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L15	51	ceramic.clm. and capillary.clm. and bonding.clm. and process	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L16	9	"6374479"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/27 01:29
L17	17	ceramic.clm. and capillary.clm. and bonding.clm. and (binder or thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L18	314	264/669.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L19	250	264/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29

L20	299	264/614.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L21	104	264/629.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:29
L22	1404	228/4.5.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:30
S1	898	capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:49
S2	431	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:50
S3	212	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:50
S4	73	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:23
S5	0	ceramic.clm. and capillary.in. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:51

S6	0	ceramic.clm. and capillary.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:51
S7	572	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:51
S8	181	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/27 01:28
S9	57	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:57
S10	572	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 20:57
S11	34	ceramic.clm. and capillary.clm. and "264"/$8.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 21:01
S12	181	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 21:01
S13	57	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 21:01

S14	51	ceramic.clm. and capillary.clm. and bonding.clm. and process	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:06
S15	46	("2892924" | "3538205" | "3660050" | "3986653" | "4020543" | "4171477" | "4182947" | "4315128" | "4331048" | "4387283" | "4390771" | "4502983" | "4513190" | "4691854" | "4705204" | "4897710" | "4909427" | "4998002" | "5178742" | "5180093" | "5214259" | "5217154" | "5280979" | "5290507" | "5367956" | "5463197" | "5463896" | "5491605" | "5527441" | "5544804" | "5601740" | "5616257" | "5649355" | "5651901" | "5676856" | "5797388" | "5816472" | "5827470" | "5931368" | "6030472" | "6073827").PN. OR ("6354479"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/25 21:50
S16	9	"6374479"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/25 21:50
S17	10	ceramic.clm. and capillary.clm. and bonding.clm. and binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:06
S18	17	ceramic.clm. and capillary.clm. and bonding.clm. and (binder or thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 22:16